

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



286 SERIES

ALUMINUM AND COPPER LOW-COST WAVE-SOLDERABLE
HEAT SINKS

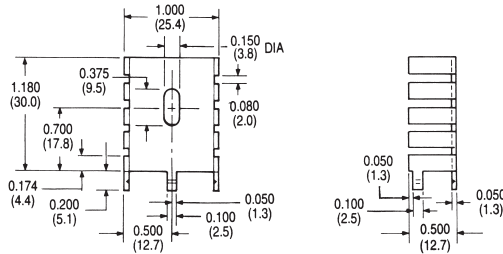
TO-220

Efficient heat removal at low cost can be achieved by inserting the **286 Series** directly into pre-drilled circuit boards; scored mounting tabs may be bent after insertion to provide added stability. The **286 Series** can be wave-soldered directly to the board. See also 286DB Series on page 55.

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Material	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
286-AB	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Aluminum, Anodized	58°C @ 4W	7.4°C/W @ 200 LFM	0.0085 (3.86)
286-CBTE	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Black	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)
286-CTE	1.190 (30.2)	1.000 (25.4) x 0.500 (12.7)	Copper, Tinned	58°C @ 4W	7.4°C/W @ 200 LFM	0.0250 (11.34)

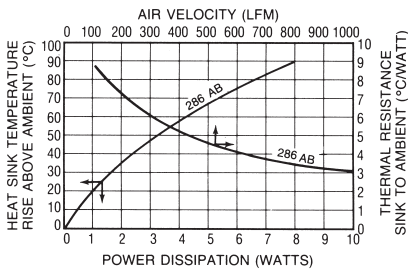
Material: 286-AB style (aluminum, black anodized), 286-CBT style (copper, black paint tin tabs), and 286-CT style (copper, tinned).

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

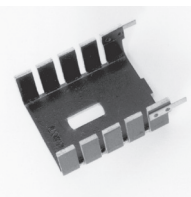
NATURAL AND FORCED
CONVECTION CHARACTERISTICS



TO-220

WAVE-SOLDERABLE LOW-COST HEAT SINKS

287 SERIES

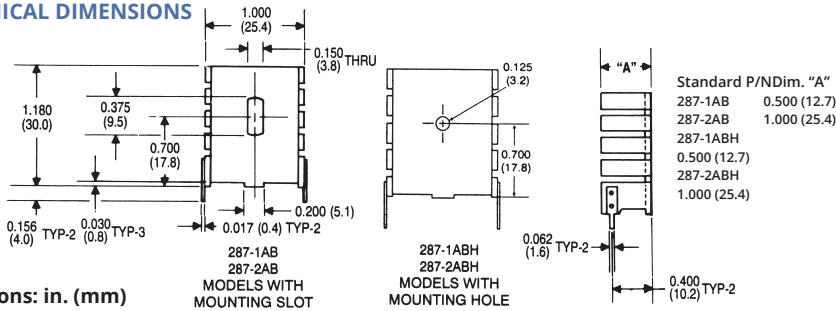


Mount these cost-effective TO-220 heat sinks vertically into pre-drilled printed circuit boards. Soldered, pre-tinned tabs can be wavesoldered directly to the board. A 0.375 in. (9.5 mm) mounting slot allows for correct positioning of TO-220 and similar semiconductor packages.

Standard P/N		Height Above PC Board in. (mm)	Maximum Footprint "A" in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
Mounting Slot	Mounting Hole			Natural Convection	Forced Convection	
287-1ABE	287-1ABH	1.180 (30.0)	1.000 (25.4) x 0.500 (12.7)	65°C @ 4W	7.8°C/W @ 200 LFM	0.0090 (4.08)
287-2ABE	287-2ABH	1.180 (30.0)	1.000 (25.4) x 1.000 (25.4)	55°C @ 4W	6.4°C/W @ 200 LFM	0.0140 (6.35)

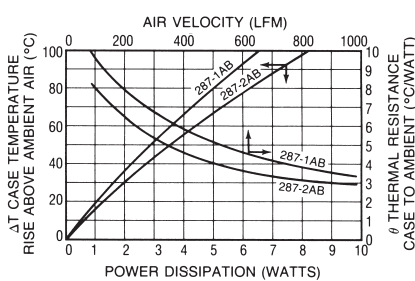
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED
CONVECTION CHARACTERISTICS



695 SERIES

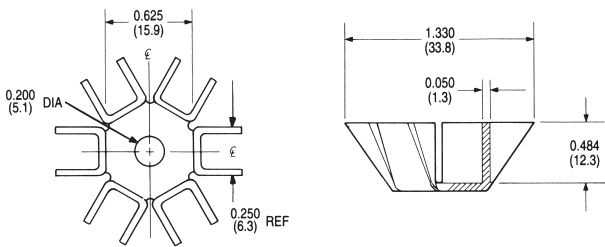
SPACE-SAVING HEAT SINKS FOR SMALL
STUD-MOUNTED DIODES

Stud-Mount

Mount and effectively heat sink small stud-mounted diodes with the **695 Series** space-saving heat sink type. Each unit is black anodized aluminum with an 0.200 in. (5.1) dia. mounting hole centered in the base. The folded fin design provides good heat dissipation for use where height is limited above the printed circuit board or base plate.

Standard P/N	Maximum Width in. (mm)	Height in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
695-1B	1.330 (33.8)	0.530 (13.7)	72°C @ 4.0W	5.2°C/W @ 400 LFM	0.008 (4.0)

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED
CONVECTION CHARACTERISTICS

